

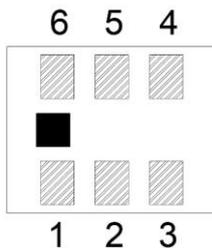
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

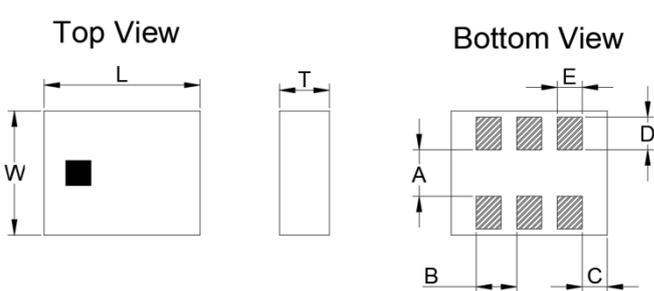
NO.	Parameter		SPEC		
			MIN	Typ	MAX
1	Low_Band Insertion Loss (dB)	700~2400 MHz	-	1.90 dB	2.50 dB
	High_Band Insertion Loss (dB)	2500~2700 MHz	-	2.10 dB	2.50 dB
2	Low_Band Return Loss (dB)	700~2400 MHz	10 dB	14 dB	-
	High_Band Return Loss (dB)	2500~2700 MHz	10 dB	14 dB	-
3	Low_Band Attenuation (dB)	2500~2700 MHz	10 dB	14 dB	-
		3300~4200 MHz	15 dB	18 dB	-
		4400~5000 MHz	18 dB	20 dB	-
	High_Band Attenuation (dB)	450~960 MHz	16 dB	18 dB	-
		1427~1710 MHz	16 dB	18 dB -	-
		1710~2400 MHz	10 dB	16 dB	-
4	Isolation	700~2400 MHz	15 dB	16 dB	-
		2500~2700 MHz	15 dB	15 dB	-
5	Port Impedance		50Ω		

Construction



PIN	Connection	PIN	Connection
P1	GND	P4	Higher Port
P2	Common Port	P5	GND
P3	GND	P6	Low Port

Dimensions

Figure	Symbol	Dimension (mm)
	L	2.50 ± 0.10
	W	2.00 ± 0.10
	T	0.95MAX
	A	0.75 ± 0.10
	B	0.65 ± 0.15
	C	0.40 ± 0.10
	D	0.53 ± 0.10
E	0.40 ± 0.05	

Typical Electrical Characteristics (T=25°C)

